

A FEATURES

- Small dimensions
- Prevention of common mode noise at high frequency
- Operating Temperature range from -40°C to +125°C (Including Self-heating)
- Excellent solderability



B PART NUMBER SYSTEM

2CB 2012 - 900 F
 ① ② ③ ④

①	Series	②	Dimension Code (L*W*H) (mm)	
2CB	Series Code		2012 (2.0×1.2×1.2)	3216 (3.2×1.6×1.8)
③	Z Code	④	RoHS Compliant	
e.g.	Calculation			
900	$90 \times 10^0 \Omega = 90 \Omega$			
121	$12 \times 10^1 \Omega = 120 \Omega$			

C DRAWINGS AND DIMENSIONS

Drawings	Schematic
<p style="text-align: center;">Land Pattern</p>	

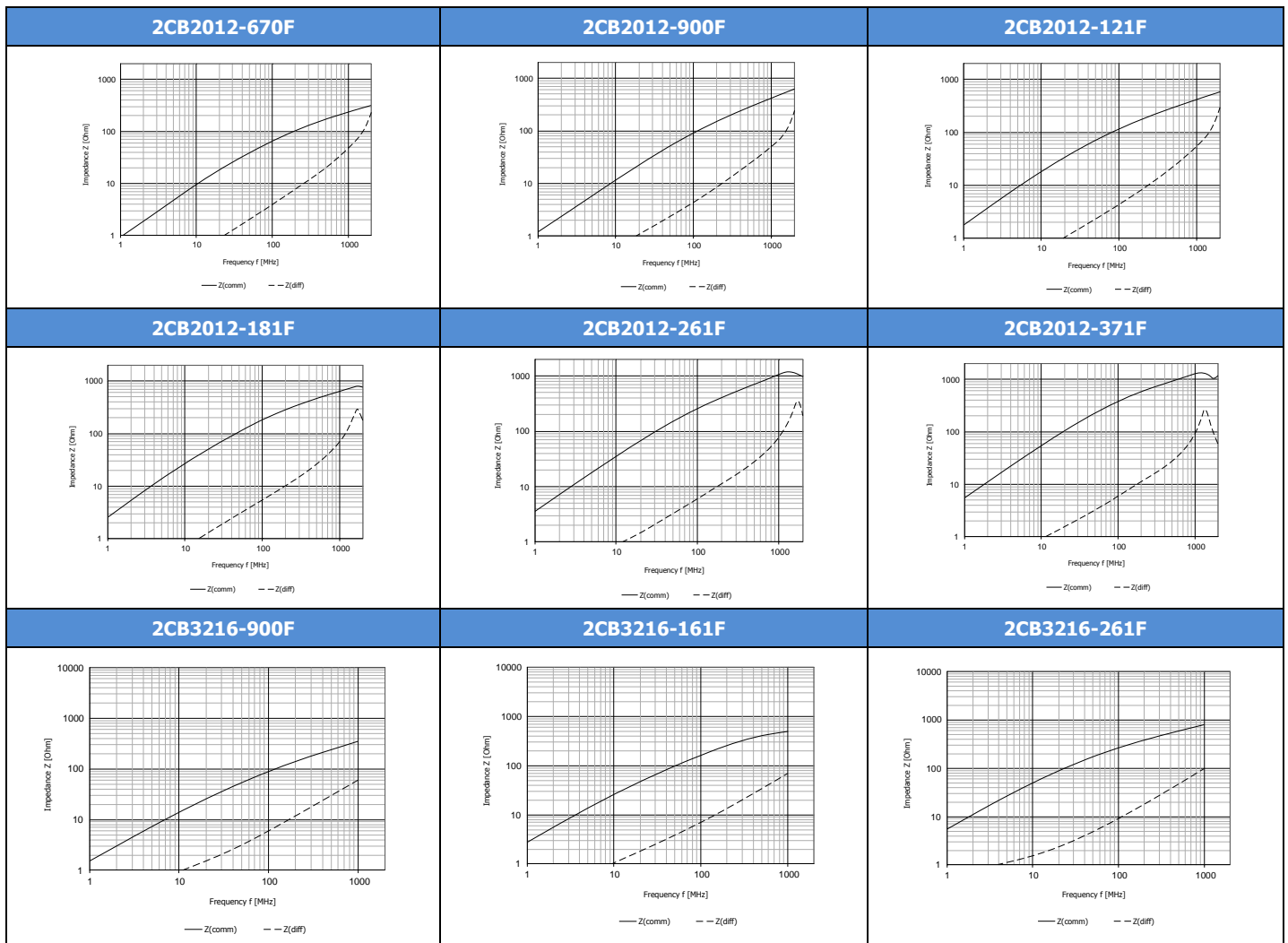
Case Size	Dimensions (mm)								
	A	B	C	D _{ref.}	E _{ref.}	H _{ref.}	I _{ref.}	J _{ref.}	L _{ref.}
2CB2012	2.0±0.2	1.2±0.2	1.2±0.2	0.5	0.45	0.4	0.4	0.9	2.6
2CB3216	3.2±0.2	1.6±0.2	1.8±0.2	0.7	0.6	0.4	0.6	1.1	3.7

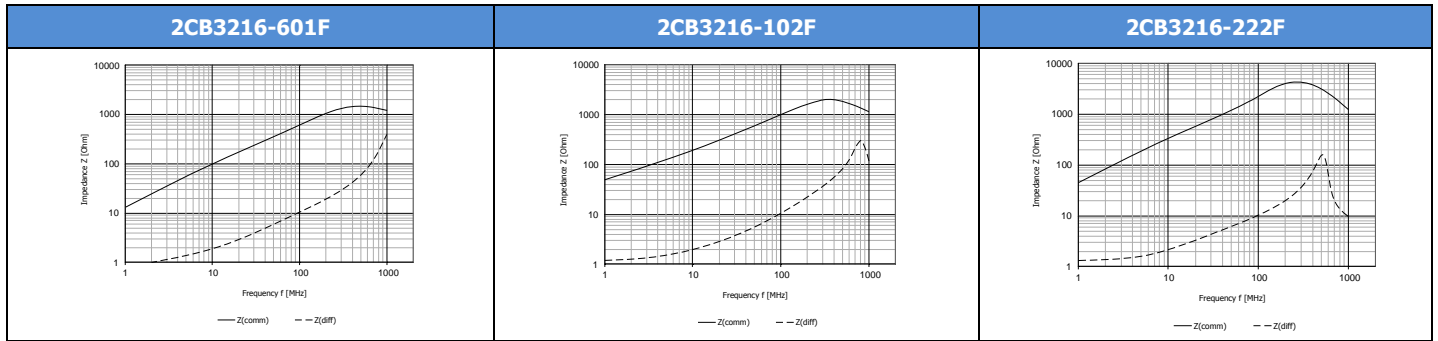
D SPECIFICATIONS

Part Number	Z@100MHz		DCR ¹	I _r ²	U _{DC}	U _T	Typ. Applications
	(Ω)	Tolerance	Max.(Ω)	(mA)	V	V(AC)	
2CB2012-670F	67	± 25 %	0.25	400	50	125	Others
2CB2012-900F	90	± 25 %	0.30	370	50	125	USB2.0
2CB2012-121F	120	± 25 %	0.30	370	50	125	IEEE1394/Firewire 400 Mbps
2CB2012-181F	180	± 25 %	0.35	330	50	125	IEEE1394/Firewire 400 Mbps
2CB2012-261F	260	± 25 %	0.40	300	50	125	Others
2CB2012-371F	370	± 25 %	0.45	280	50	125	IEEE1394/Firewire 400 Mbps
2CB3216-900F	90	± 25 %	0.30	370	50	125	USB2.0
2CB3216-161F	160	± 25 %	0.40	340	50	125	IEEE1394/Firewire 400 Mbps
2CB3216-261F	260	± 25 %	0.50	310	50	125	Others
2CB3216-601F	600	± 25 %	0.80	260	50	125	Others
2CB3216-102F	1000	± 25 %	1.00	230	50	125	Others
2CB3216-222F	2200	± 25 %	1.20	200	50	125	Others

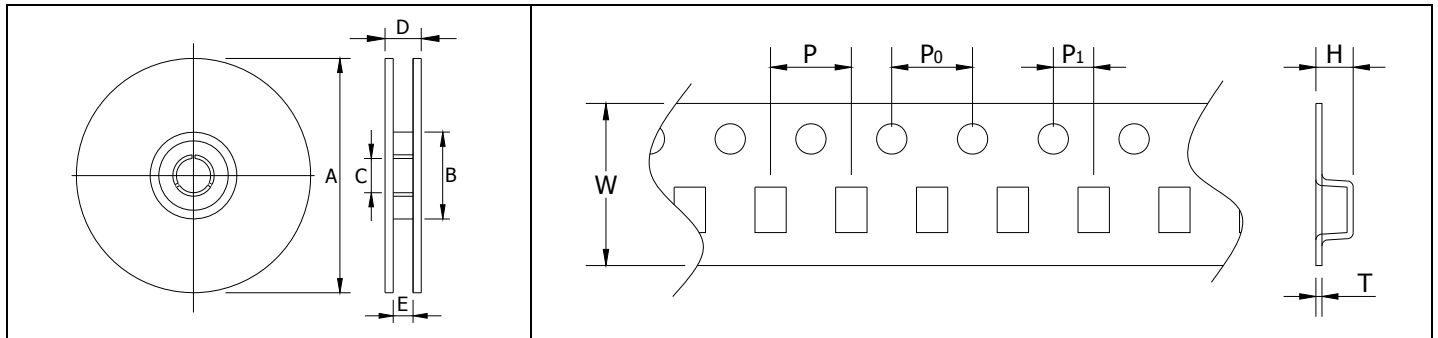
1. DCR measured @ 25°C.
2. I_r: DC current for an approximate 40°C rise from 20°C ambient temperature.
3. Specifications subject to change without notice please check our website for latest information.

E TYPICAL IMPEDANCE CURVES



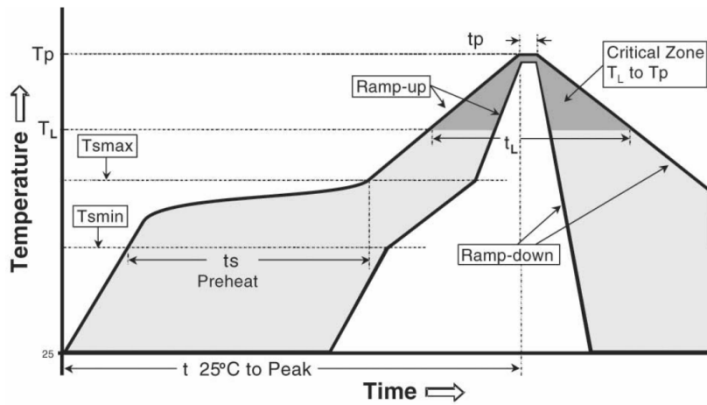


F TAPE AND REEL SPECIFICATIONS



Case Size	Parts per Reel	Reel Dimensions(REF)					Tape Dimensions(REF)					
		A	B	C	D	E	W	P	P ₀	P ₁	H	T
2CB2012	2000	178	58	13	13	9.0	8	4	4	2	1.3	0.25
2CB3216	2000	178	58	13	13	9.0	8	4	4	2	2.1	0.25

G RECOMMENDED SOLDER REFLOW PROFILE



Profile Feature	Recommended Conditions
Average ramp-up rate (Tsmax to Tp)	3°C/second max.
Preheat	
Temperature Min (Tsmmin)	100°C
Temperature Max (Tsmmax)	150°C
Time (Tsmmin to Tsmmax)(ts)	60-180 seconds
Time maintained above:	
Temperature (Tl)	217°C
Time (tl)	60-150 seconds
Peak Temperature (Tp)	See Table2
Time within 5°C of actual Peak Temperature (tp) ²	20-40 seconds
Ramp-down Rate	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max

Table 1

Package Thickness	Volume mm ³ <350	Volume mm ³ 350 - 2000	Volume mm ³ >2000
< 1.6mm	260°C	260°C	260°C
1.6mm - 2.5mm	260°C	250°C	245°C
>2.5mm	250°C	245°C	245°C

Table 2

1. The above profiles are based on IPC/JEDEC J-STD-020C.
2. Exceeding these conditions may cause lowered product reliability.